

#### **About Statek**

In 1970, Statek Corporation was the first company to use semiconductor technologies such as photolithography, chemical milling and micromachining to manufacture quartz resonators in wafer form. Today, Statek remains at the forefront of innovation in the design, development and manufacturing of highly reliable, ultra-miniature quartz-based frequency control products.

For over 50 years, we have supported military programs with state-of-the-art crystal resonators and oscillators. We offer a complete portfolio of frequency control products manufactured and tested to military standards: oscillators to MIL-PRF-55310 Product Level B and resonators to MIL-PRF-3098. Our dedicated servicing of the demanding requirements of the military market makes us a preferred supplier to most major defense contractors.

All our products are designed, manufactured and tested in the United States.

## **Technological Capability**

Statek's core competence is its ability to design and manufacture ultra-miniature resonators in quartz wafers using its patented photolithographic and chemical milling processes.

With complete vertical integration, Statek has total in-house control over the manufacturing of its products. From cutting quartz bars into wafers, to wafer lapping and polishing, to photolithographic processing and chemical milling in our Wafer Fab lines, to assembly and seal, Statek has the complete in-house capability to manufacture and test high-precision, extremely rugged and reliable ceramic-packaged quartz crystal resonators, oscillators and sensors.

Variable-size batch processing allows us to maintain efficient production with a high mix of both standard and custom devices.

#### **Materials**

We cultivate long-term relationships with our domestic suppliers to ensure stable sources of high-quality materials. We manufacture our resonators with high-grade cultured alpha-quartz. Swept quartz is also available for applications requiring radiation hardness. To simplify and minimize the device circuitry, we use oscillator-specific integrated circuits. Lastly, we design our own ceramic packages, which are then manufactured by our sister company, AdTech Ceramics.

## **Product Continuity**

Statek provides the continuity of support required for long-term military programs. In addition to maintaining complete records and traceability, we are committed to supporting the life cycle of our customers' products.



**Quality Assurance Inspection** 

## **Quality Assurance**

The entire Statek organization is committed to ensuring that its products and services meet or exceed its customers' expectations. Through continuous improvement, Statek has developed a quality system that incorporates AS9100 and ISO 9001.



**Smart Munitions** 

**Airborne Communication Systems** 

**Battlefield Simulation** 

Portable Field Equipment

**Projectile Electronics** 

**Robust Computing Platforms** 

Telemetry

**Navigation** 

**GPS** 

**Unmanned Aerial Vehicles** 

## **Military Product Features**

- Extreme high shock survivability (highest in the industry)
- Ultra-miniature and low-profile packaging
- Excellent long-term aging
- Full product traceability
- High stability and high accuracy
- Extended temperature ranges (-55°C to 225°C)
- Swept quartz available for radiation resistance
- Low power consumption
- Low acceleration sensitivity
- Manufacture and testing to MIL-PRF-55310 (Oscillators)
- Manufacture and testing to MIL-PRF-3098 (Crystals)

## **Military Program Participation**

AMRAAM ADVANCED MEDIUM-RANGE AIR TO AIR MISSILE

ASRAAM Advance Short-Range Air to Air Missile

CSEL COMBAT SURVIVOR EVADER LOCATOR

DAGR DIRECT ATTACK GUIDED ROCKET

DAS DISTRIBUTED APERTURE SYSTEM

ERGM EXTENDED RANGE GUIDED MUNITIONS

EXCALIBUR EXTENDED RANGE ARTILLERY PROJECTILE

JASSM Joint Air to Surface Standoff Missile

JCM JOINT COMMON MISSILE

JTRS JOINT TACTICAL RADIO SYSTEM

JSF JOINT STRIKE FIGHTER
LGB LASER GUIDED BOMB
M762/M767 ET FUZE PROGRAMS

MRM MEDIUM RANGE MUNITION

PAC-3 PATRIOT ADVANCED CAPABILITY-3

PGK PRECISION GUIDANCE KIT
SFW SENSOR FUZED WEAPON
SM-3 STANDARD MISSILE-3

SYSI Systems Serial Interface

WCMD WIND CORRECTED MUNITIONS DISPENSER







# STXOHG **Tight Stability** ±5 ppm -40°C to +85°C 3.2 x 2.5 mm SMD

## FEATURED PRODUCT

#### **FEATURES**

- 3.2 x 2.5 mm hermetically sealed ceramic package
- High shock resistance up to 75,000 g
- Tight frequency stability and low phase noise
- **Ultra-low Allan deviation and** phase jitter
- Ultra-low period jitter (1.4 ps rms)
- Low acceleration sensitivity
- Low current consumption; 3.0 mA max no load across temperature
- Full military testing available
- CMOS output; enable/disable with tri-state
- Fundamental frequency; no PLL artifacts
- IBIS model available
- Designed and manufactured in the USA

## SURFACE MOUNT OSCILLATORS



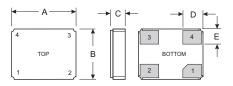
#### **STXOHG**

Frequency Range	10 MHz to 70 MHz
Supply Voltage	2.5 V to 3.3 V ±10%
Total Frequency Tolerances	±5 ppm (Industrial)
Typical Supply Current <sup>1</sup>	3.0 mA
Output Voltage Levels	$V_{OH} > V_{DD} - 0.4 V$
	V <sub>OL</sub> < 0.4 V
Output Load (CMOS)	15 pF
Start-up Time	5 ms MAX
Rise/Fall Time	5 ns MAX
Duty Cycle	45% MIN, 55% MAX
Aging, first year	2 ppm MAX
Shock Survival <sup>2</sup>	Up to 75,000 g, 0.5 ms, 1/2 sine
Vibration Survival <sup>3</sup>	20 g, 10-2,000 Hz swept sine
Operating Temperature Ranges	-40°C to +85°C (Industrial)
	-55°C to +125°C (Military)
Storage Temperature Range	-55°C to +125°C
Typical Period Jitter (rms)	1.4 ps over 10,000 cycles
MAX Process Temperature	260°C for 20 seconds
MIN/MAX Supply Voltage (V <sub>DD</sub> )	-0.3 V / 4.0 V
MIN/MAX Enable/Disable Pin Voltage (V <sub>IN</sub> )	-0.3 V / V <sub>DD</sub> + 0.3 V
Moisture Sensitivity Level (MSL): This product is herme	etically sealed and is not moisture sensitive.

- 1. V<sub>DD</sub> = 3.3V, 15 pF load, frequency at 40 MHz.
- 2. HG options for frequencies up to 50 MHz. Contact factory for HG options above 50 MHz.
- 3. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available. All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

#### **STXOHG**



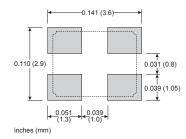
#### PIN CONNECTIONS

- Enable/Disable (E) or not connected (N)
- 2 Ground
- Output
- 4  $V_{DD}$

#### **DIMENSIONS**

	IY	Ρ.	IVIA	Х.
DIM	inches	mm	inches	mm
Α	0.126	3.20	0.136	3.40
В	0.099	2.50	0.107	2.70
$C_{(SM1)}$	0.039	1.00	0.053	1.35
C(SM3/SM5)	0.044	1.12	0.058	1.47
D	0.040	1.00	0.041	1.10
E	0.030	0.75	0.031	0.85

#### SUGGESTED LAND PATTERN



## SURFACE MOUNT OSCILLATORS



#### **CXOXLPNR**

	3.2	x2.5 mm			
Frequency Range	20 [	MHz to 1	25	MHz	
Supply Voltage	1.8	V to 3.3	V ±	:10%	
Calibration Tolerance <sup>1</sup>	±10	0 ppm to	) ±5	50 ppm	
Frequency-Temperature Stability <sup>2,3</sup>	±10	0 ppm to	±3	30 ppm (li	ndustrial)
	±10	0 ppm to	) ±5	50 ppm (N	/lilitary)
Typical Supply Current		1.8 V		2.5 V	3.3 V
at 15 pF Output Load (mA)	25 MHz	1.3 mA		1.8 mA	2.8 mA
	50 MHz	2.3 mA		3.2 mA	4.7 mA
	100 MHz	4.5 mA		6.1 mA	8.3 mA
	125 MHz	7.2 mA		10.0 mA	12.9 mA
Output Load (CMOS)	15 բ	ρF			
Start-up Time	5 m	s MAX			
Rise/Fall Time	2 ns	S TYP			
Duty Cycle	45%	6 MIN, 5	5%	MAX	
Aging, first year	2 pp	m MAX			
Shock Survival <sup>4</sup>	Up to 100,000 g, 0.3 ms, 1/2 sine				
Vibration Survival <sup>5</sup>	20 g, 10-2,000 Hz swept sine				
Operating Temperature Ranges	-40°	°C to +85	5°C	(Industria	al)
	-55	°C to +12	25°(	C (Military	/)

Moisture Sensitivity Level (MSL): This product is hermetically sealed and is not moisture sensitive.

- 1. Tighter tolerances available. Contact factory.
- 2. Does not include calibration tolerance. Tighter tolerances available.
- 3. Broader temperature ranges available. Contact factory.
- Contact factory for higher shock options for frequencies greater than 50 MHz.
- 5. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available. All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

For packaged swept quartz crystals, see model SWCX1 on our website

## **CXOXLPNR**

Radiation Tolerant
High Shock Resistance
1.8 V to 3.3 V
-55°C to +125°C
3.2 x 2.5 mm SMD

## FEATURED PRODUCT

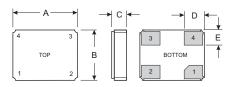
#### **FEATURES**

- 30 kRad (Si) total ionizing dose tolerant
- High shock resistance, 3-point crystal mount as required by NASA EEE-INST-002
- 100,000 g option
- CMOS output with enable/disable
- Low phase noise and jitter
- Full military testing available
- Low acceleration sensitivity
- Wide supply voltage (1.8 V to 3.3 V)
- No PLL artifacts
- Hermetically sealed ceramic package
- IBIS model available
- Designed and manufactured in the USA

Please visit our website to see the complete **CXOXLPNR** datasheet for further information on phase noise and jitter performance.

#### **CXOXLPNR**

Phase Jitter



#### PIN CONNECTIONS

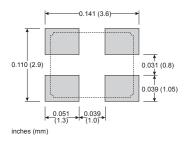
- 1 Enable/Disable (E) or not connected (N)
- 2 Ground
- 3 Output
- 4 V<sub>DD</sub>

#### DIMENSIONS

150 fs (rms) typical over 12 kHz to 20 MHz (50 MHz)

	TYI	٥.	MA	X.
DIM	inches	mm	inches	mm
Α	0.126	3.20	0.136	3.40
В	0.099	2.50	0.107	2.70
$C_{(SM1)}$	0.039	1.00	0.043	1.09
C(SM3/SM5)	0.044	1.12	0.048	1.21
D	0.040	1.00	0.041	1.10
E	0.030	0.75	0.031	0.85

#### SUGGESTED LAND PATTERN



## **CXOLATHG**

Ultra Low Current
High Shock Resistance
1.8 V to 3.3 V
16.0 kHz - 32.768 kHz
3.2 x 1.5 mm SMD

## FEATURED PRODUCT

#### **FEATURES**

- Ultra low power (Less than 1 μA; V<sub>DD</sub>=3.3V, OE "Low")
- Fast start-up (typical 3 ms)
- Tight frequency tolerance
- High shock resistance (30,000 g and higher)
- Low acceleration sensitivity (typically 0.5 ppb/g)
- Low aging
- CMOS output
- · Optional output enable/disable with tri-state
- Hermetically sealed ceramic package
- Full military testing available
- IBIS model available
- Designed and manufactured in the USA

## SURFACE MOUNT OSCILLATORS



#### **CXOLATHG**

3.2x1.5 mm

Output Frequency	16.0 kHz to 32.768 kHz
Supply Voltage	1.8 V to 3.3 V ±10%
Calibration Tolerance <sup>1</sup>	±25 ppm
Frequency Stability Over Temperature <sup>2</sup>	±20 ppm to ±50 ppm (Industrial)
	±35 ppm to ±50 ppm (Military)
Typical Supply Current	10 μΑ
	< 1 µA when disabled
Output Voltage Levels	$V_{OH} > 0.9 V_{DD}$
	$V_{OL}$ < 0.1 $V_{DD}$
Output Load (CMOS)	15 pF
Aging, first year	3 ppm MAX
Shock Survival	Up to 100,000 g, 0.3 ms, 1/2 sine
Vibration Survival <sup>3</sup>	20 g, 10-2,000 Hz swept sine
Operating Temperature Ranges	-40°C to +85°C (Industrial)
	-55°C to +125°C (Military)
Start-up Time	16.384 kHz: 5 ms TYP
	32.768 kHz: 3 ms TYP
Rise/Fall Time (10%-90%)	t <sub>r</sub> : 7 ns TYP, 10 ns MAX
	t <sub>f</sub> : 5 ns TYP, 10 ns MAX
Duty Cycle	45% MIN, 55% MAX
Storage Temperature Range	-55°C to +125°C
MAX Process Temperature	260°C for 20 seconds
MIN/MAX Supply Voltage (V <sub>DD</sub> )	-0.3 V / 4.0 V
MIN/MAX Enable/Disable Pin Voltage (V <sub>IN</sub> )	-0.3 V / V <sub>DD</sub> + 0.3 V
Moisture Sensitivity Level (MSL): This product is herme	etically sealed and is not moisture sensitive.

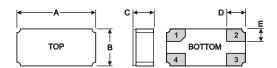
- 1. Other tolerances available. Contact factory.
- 2. Does not include calibration tolerances. Other tolerances available. Contact factory.
- 3. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available.

All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

#### Please contact the factory for **Higher Frequency** options

#### **CXOLATHG**



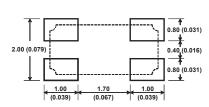
## PIN CONNECTIONS

- 1 Output
- 2 Ground
- 3 Enable/Disable (E) or not connected (N)
- 4 V<sub>DD</sub>

#### DIMENSIONS

	TYI	MA	X.	
DIM	inches	mm	inches	mm
Α	0.126	3.20	0.130	3.30
В	0.059	1.50	0.063	1.60
$C_{(SM1)}$	0.037	0.95	0.039	1.00
D	0.029	0.75	0.030	0.77
Е	0.020	0.50	0.021	0.52

#### SUGGESTED LAND PATTERN



mm (inches)

## SURFACE MOUNT OSCILLATORS



#### **CXOXLPNHG**

		UXLPN		<u> </u>	
		x2.5 mm			
Frequency Range		MHz to 1			
Supply Voltage <sup>1</sup>		V to 5.0			
Calibration Tolerance <sup>2</sup>	±10	0 ppm to	) ±	50 ppm	
Frequency-Temperature Stability <sup>3,4</sup>	±10	0 ppm to	t c	30 ppm (I	Industrial)
	±10	0 ppm to	) ±5	50 ppm (l	Military)
Typical Supply Current		1.8 V		2.5 V	3.3 V
at 15 pF Output Load	10 MHz	1.1 mA		1.9 mA	3.2 mA
	20 MHz	1.6 mA		3.0 mA	5.0 mA
	25 MHz	1.3 mA		1.8 mA	2.8 mA
	50 MHz	2.3 mA		3.2 mA	4.7 mA
	100 MHz	4.5 mA		6.1 mA	8.3 mA
	125 MHz	7.2 mA		10.0 mA	12.9 mA
Output Load (CMOS)	15 բ	ρF			
Start-up Time	5 m	s MAX			
Rise/Fall Time	2 ns	s TYP			
Duty Cycle	45%	6 MIN, 5	5%	MAX	
Aging, first year	3 pp	om MAX			
Shock Survival <sup>5</sup>	Up	to 100,0	00	g, 0.5 s,	1/2 sine
Vibration Survival <sup>6</sup>	20 (	g, 10-2,0	00	Hz swep	t sine
Operating Temperature Ranges		-		(Industri	
	-55°C to +125°C (Military)				•
Storage Temperature Range		°C to +1		,	
MAX Process Temperature	260	°C for 20	) se	econds	
MIN/MAX Supply Voltage (V <sub>DD</sub> )	-0.3	8 V / 4.0	V		
Phase Jitter	75 f	fs TYP, 1	2 k	Hz to 20	MHz

Moisture Sensitivity Level (MSL): This product is hermetically sealed and is not moisture sensitive.

- 1. 5.0V available, 10 MHz to 60 MHz (3.8 mA @ 25 MHz)
- 2. Tighter tolerances available. Contact factory.
- 3. Does not include calibration tolerance. Tighter tolerances available
- 4. Broader temperature ranges available. Contact factory.
- 5. Contact factory for higher shock options for frequencies greater than 50 MHz.
- 6. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.

## **CXOXLPNHG**

Low Phase Noise
High Shock Resistance
1.8 V to 5.0 V
-55°C to +125°C
3.2 x 2.5 mm SMD

## FEATURED PRODUCT

#### **FEATURES**

Period Jitter – 1 ps (rms) typical for 125 MHz Phase Jitter – 75 fs (12 kHz to 20 MHz) typical for 125 MHz

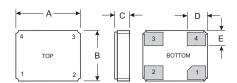
- Hermetically sealed ceramic package
- High shock resistance (HG version) up to 100,000 g
- · CMOS output with enable/disable
- Low phase noise, jitter and Allan deviation
- Operation over -55°C to +125°C
- Low acceleration sensitivity
- Wide supply voltage (1.8 V to 5.0 V)
- No PLL artifacts
- · Full military testing available
- IBIS model available
- Designed and manufactured in the USA

#### Notes:

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available.

All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

#### CXOXLPNHG



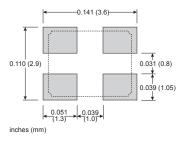
#### PIN CONNECTIONS

- 1 Enable/Disable (E) or not connected (N)
- 2 Ground
- 3 Output
- 4 V<sub>DD</sub>

#### DIMENSIONS

	IYP		MAX	<.
DIM	inches	mm	inches	mm
Α	0.126	3.20	0.136	3.40
В	0.099	2.50	0.107	2.70
C(SM1)	0.039	1.00	0.043	1.09
C(SM3/SM5)	0.044	1.12	0.048	1.21
D	0.040	1.00	0.041	1.10
E	0.030	0.75	0.031	0.85

#### SUGGESTED LAND PATTERN







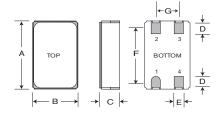
## SURFACE MOUNT OSCILLATORS

	<b>HGXO</b> 5.0x7.5 mm		6.5x5.0 mm		
Frequency Range	460 kHz to 50 MHz		32.768 kHz to 160 MHz		
, , ,			(up to 200 MHz for 3.3V)		
Supply Voltage	1.8 V to 5.0 V		1.8 V to 5.0 V		
Standard Calibration Tolerances <sup>1</sup>	±10 ppm, ±25 p	pm, ±50 ppm, ±100 ppm	±25 ppm, ±50 p	pm, ±100 ppm	
Frequency Stability Over Temp. Range <sup>2</sup>	±25 ppm to ±10	00 ppm	±25 ppm to ±10	00 ppm	
Standard Operating Temperature Ranges	-40°C to +85°C	/ -55°C to +125°C	-40°C to +85°C	/ -55°C to +125°C	
Supply Current (Typical)	3.3 V	5.0 V	3.3 V	5.0 V	
	10 mA for 50 MHz	14 mA for 50 MHz	10 mA for 50 MHz	14 mA for 50 MHz	
	8 mA for 40 MHz	12 mA for 40 MHz	8 mA for 40 MHz	12 mA for 40 MHz	
	6 mA for 30 MHz	10 mA for 30 MHz	6 mA for 30 MHz	10 mA for 30 MHz	
	4 mA for 24 MHz	8 mA for 24 MHz	4 mA for 24 MHz	8 mA for 24 MHz	
Output Load (CMOS) <sup>3</sup>	15 pF		15 pF		
Start-up Time	5 ms MAX		5 ms MAX		
Rise/Fall Time	6 ns MAX		3 ns TYP, 6 ns l	MAX	
Duty Cycle <sup>1</sup>	45% MIN, 55% MAX 45% MIN, 55% MAX		MAX		
Aging, first year	AGING IS DEPENDENT ON FREQUENCY AND OTHER DESIGN CONSIDERATIONS. PLEASE CONTAC		TIONS. PLEASE CONTACT FACTORY.		
Shock, survival	Up to 100,000 (	g, 0.5 ms, 1/2 sine	Up to 100,000 g, 0.5 ms, 1/2 sine		
Vibration, survival <sup>4</sup>	20 g, 10-2000 H	Iz swept sine	20 g, 10-2000 F	Iz swept sine	
1. Other televenese sysilable					

<sup>1.</sup> Other tolerances available.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available. All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

#### **HGXO**



#### PIN CONNECTIONS

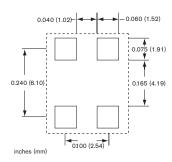
- Enable/Disable (E or T) or not connected (N)
- 2 Ground
- Output
- 4 VDD

#### DIMENSIONS

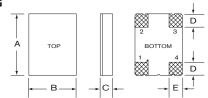
	TTP.		IVIAA	
DIM	inches	mm	inches	mm
Α	0.295	7.50	0.302	7.68
В	0.197	5.00	0.204	5.18
C*	0.089	2.25	0.098	2.50
D	0.055	1.40		
E	0.040	1.02		
F	0.240	6.10		
G	0.100	2.54		

\* SM1 (Termination material is Au over Ni over W). Solder dip (SM3 and SM5) also available.

#### SUGGESTED LAND PATTERN



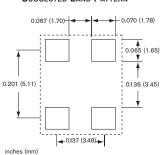
### **CXOMKHG**



- Enable/Disable (E or T) or not connected (N)
- 2 Ground
- 3 Output
- 4 VDD

#### DIMENSIONS

	TYP	MAX	ζ.	
DIM	inches	mm	inches	mm
Α	0.256	6.50	0.263	6.68
В	0.197	5.00	0.204	5.18
C(SM1)	0.055	1.34	0.060	1.52
C(SM3/SM5	0.060	1.52	0.065	1.65
D	0.055	1.40	0.065	1.65
Е	0.060	1.52	0.070	1.78



<sup>2.</sup> Does not include calibration tolerance. Other tolerances available.

TTL loads and higher CMOS loads available. Contact Factory.
 Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.





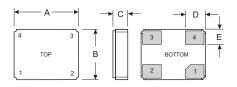


CXOXHG					
3.2x2.5 mm		2.5x2.0 mr	2.5x2.0 mm		
16 kHz to 160 M	16 kHz to 1	16 kHz to 100 MHz			
1.8 V to 5.0 V	1.8 V to 5.0	1.8 V to 5.0 V			
±25 ppm, ±50 p	pm, ±100 ppm	±25 ppm, ±	50 ppm, ±100	ppm	
±25 ppm to ±10	0 ppm	±25 ppm to ±	£100 ppm		
-40°C to +85°C	/ -55°C to +125°C	-40°C to +8	5°C / -55°C to	+125°C	
1.8 V	3.3 V	1.8 V	3.3 V		
2.6 mA for 50 MHz	4.5 mA for 50 MHz	3 mA for 50 M	Hz 6 mA f	or 50 MHz	
1.8 mA for 32 MHz	3.0 mA for 32 MHz	2 mA for 32 M	Hz 3 mA f	or 32 MHz	
1.4 mA for 24 MHz	2.3 mA for 24 MHz	1.5 mA for 24	MHz 3 mA f	or 24 MHz	
68 μA for 32.768 kHz	75 μA for 32.768 kHz	115 µA for 32.7	'68 kHz 125 μA	for 32.768 kHz	
15 pF		15 pF	15 pF		
5 ms MAX (0.6	ms for 32.768 kHz)	5 ms MAX (	5 ms MAX (1 ms for 32.768 kHz)		
6 ns MAX (20 ns	s for 32.768 kHz)	6 ns MAX (6	6 ns for 32.768	8 kHz)	
45% MIN, 55% MAX		45% MIN, 5	45% MIN, 55% MAX		
AGING IS DEPENDE	OTHER DESIGN CONSID	ERATIONS. PLEA	SE CONTACT FACTORY		
Up to 100,000 g	Up to 75,00	Up to 75,000 g, 0.5 ms, 1/2 sine			
20 g, 10-2000 H	Iz swept sine	20 g, 10-20	20 g, 10-2000 Hz swept sine		
	3.2x2.5 mm  16 kHz to 160 M  1.8 V to 5.0 V  ±25 ppm, ±50 p  ±25 ppm to ±10  -40°C to +85°C  1.8 V  2.6 mA for 50 MHz  1.8 mA for 32 MHz  1.4 mA for 24 MHz  68 µA for 32.768 kHz  15 pF  5 ms MAX (20 ns  45% MIN, 55%  AGING IS DEPENDE  Up to 100,000 g	3.2x2.5 mm  16 kHz to 160 MHz  1.8 V to 5.0 V  ±25 ppm, ±50 ppm, ±100 ppm  ±25 ppm to ±100 ppm  -40°C to +85°C / -55°C to +125°C  1.8 V  3.3 V  2.6 mA for 50 MHz  1.8 mA for 32 MHz  1.4 mA for 24 MHz  68 µA for 32.768 kHz  15 pF  5 ms MAX (0.6 ms for 32.768 kHz)  6 ns MAX (20 ns for 32.768 kHz)  45% MIN, 55% MAX	3.2x2.5 mm  16 kHz to 160 MHz  1.8 V to 5.0 V  ±25 ppm, ±50 ppm, ±100 ppm  ±25 ppm to ±3 ppm to ±40°C to +85°C / -55°C to +125°C  1.8 V  2.6 mA for 50 MHz  1.8 mA for 50 MHz  1.8 mA for 32 MHz  3.0 mA for 32 MHz  3 mA for 32 M  1.4 mA for 24 MHz  2.3 mA for 32 MHz  1.5 mA for 32 M  1.5 mA for 50 M  1.6 mA for 32 M  1.7 mA for 32 M  1.8 v  1.8	3.2x2.5 mm       2.5x2.0 mm         16 kHz to 160 MHz       16 kHz to 100 MHz         1.8 V to 5.0 V       1.8 V to 5.0 V         ±25 ppm, ±50 ppm, ±100 ppm       ±25 ppm, ±50 ppm, ±100 ppm         -40°C to +85°C / -55°C to +125°C       -40°C to +85°C / -55°C to         1.8 V       3.3 V         2.6 mA for 50 MHz       4.5 mA for 50 MHz       3 mA for 50 MHz       6 mA for 32 MHz         1.8 mA for 32 MHz       3.0 mA for 32 MHz       2 mA for 32 MHz       3 mA for 24 MHz         1.4 mA for 24 MHz       2.3 mA for 24 MHz       1.5 mA for 24 MHz       3 mA for 32.768 kHz         15 pF       15 pF         5 ms MAX (0.6 ms for 32.768 kHz)       5 ms MAX (1 ms for 32.768 kHz)         6 ns MAX (20 ns for 32.768 kHz)       6 ns MAX (6 ns for 32.768 kHz)         45% MIN, 55% MAX       45% MIN, 55% MAX         AGING IS DEPENDENT ON FREQUENCY AND OTHER DESIGN CONSIDERATIONS. PLEA         Up to 100,000 g, 0.5 ms, 1/2 sine       Up to 75,000 g, 0.5 ms, 1/2	

- 1. Not all frequencies are available under 1 MHz. Contact factory. 2. Not all voltages are available at all frequencies. Contact factory.
- 3. Other tolerances available. 4. Does not include calibration tolerance. Other tolerances available.
  5. TTL loads and higher CMOS loads available. Contact Factory. 6. Maximum rise/fall times for 32.768 kHz are at 3.3 V. Contact factory for rise/fall times at other voltages.
  7. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available. All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

#### **CXOXHG**



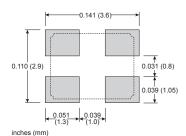
#### PIN CONNECTIONS

- Enable/Disable (E) or not connected (N)
- 2 Ground
- 3 Output
- VDD 4

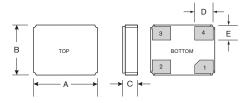
#### DIMENSIONS

	TYF	Р.	MAX.		
DIM	inches	mm	inches	mm	
Α	0.126	3.20	0.136	3.40	
В	0.099	2.50	0.107	2.70	
$C_{(SM1)}$	0.039	1.00	0.043	1.09	
C(SM3/SM5)	0.044	1.12	0.048	1.21	
D	0.040	1.00	0.041	1.10	
E	0.030	0.75	0.031	0.85	

#### SUGGESTED LAND PATTERN



### **CXOQHG**

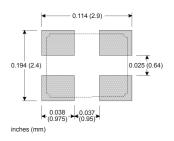


#### PIN CONNECTIONS

- Enable/Disable (E) or not connected (N)
- 2 Ground
- 3 Output
- 4 VDD

#### DIMENSIONS

	TYF	Р.	MAX.		
DIM	inches	mm	inches	mm	
Α	0.098	2.50	0.102	2.60	
В	0.079	2.00	0.083	2.10	
C(SM1)	0.035	0.89	0.039	1.00	
C(SM3/SM5)	0.040	1.02	0.048	1.22	
D	0.026	0.67	0.027	0.69	
E	0.022	0.57	0.023	0.59	







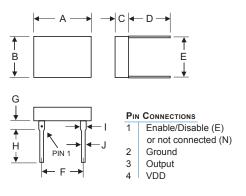
#### **LHGAT**

	5.0x7.0 mm w/	Leads			
Frequency Range	320 kHz to 50 MHz				
			_		
Supply Voltage	1.8 V to 5.0 V				
Standard Calibration Tolerances <sup>1</sup>	±20 ppm and up	)			
Frequency Stability Over Temp. Range <sup>2</sup>	±40 ppm to ±10	0 ppm			
Standard Operating Temperature Ranges	-40°C to +85°C	/ -55°C to +125°C			
Supply Current (Typical)	3.3 V	5.0 V	П		
	6.0~mA for $50~MHz$	13 mA for 50 MHz			
	5.5~mA for 40 MHz	12 mA for 40 MHz			
	5.0~mA for $32~MHz$	10 mA for 32 MHz			
	3.0 mA for 24 MHz	8.0 mA for 24 MHz			
Output Load (CMOS) <sup>3</sup>	15 pF				
Start-up Time	5 ms MAX		٦		
Rise/Fall Time	4 ns TYP, 8 ns I	MAX			
Duty Cycle <sup>1</sup>	45% MIN, 55%	MAX			
Aging, first year <sup>4</sup>	See note 4 belo	W			
Shock, survival	Up to 100,000 g	g, 0.5 ms, 1/2 sine			
Vibration, survival <sup>5</sup>	20 g, 10-2000 F	Iz swept sine			

- 1. Other specifications available.
- Does not include calibration tolerance. Other tolerances available.
- 3. TTL loads and higher CMOS loads available. Contact Factory.
- 4. Aging is dependent on frequency and other design considerations. Please contact factory.
- 5. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available. All parameters are measured at an ambient temperature with a 10 M $\Omega$ , 15 pF load.

#### **LHGAT**



DIMENSIONS	6
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	TYI	Р.	MA	١X.
DIM	inches	mm	inches	mm
Α	0.276	7.00	0.281	7.14
В	0.197	5.00	0.202	5.13
С	0.065	1.65	0.070	1.78
D	0.200	5.08	0.205	5.20
E	0.195	4.90	0.205	5.20
F	0.200	5.08	0.205	5.20
G	0.040	1.02		
Н	0.160	4.06		
I	0.028	0.71		
J	0.018	0.46	0.021	0.53



#### **Absolute Maximum Ratings**

Supply Voltage  $V_{\scriptscriptstyle DD}$ 

Nominal voltage < 4.0 V -0.5 V to 4.0 V Nominal voltage ≥ 4.0 V -0.5 V to 7.0 V Storage Temperature -55°C to +125°C Maximum Process Temp. 260°C for 20 seconds

#### **Enable / Disable Options (E/T/N)**

Statek offers three enable/disable options: E, T, and N. Both the E-version and T-version have Tri-State outputs and differ in whether the oscillator continues to run internally when the output is put into the high Z state: it stops in the E-version and continues to run in the T-version. So, the E-version offers very low current consumption when the oscillator is disabled and the T-version offers very fast output recovery when the oscillator is reenabled. The N-version does not have PIN 1 connected internally and so has no enable/ disable capability. The following table summarizes the three options.

<b>→</b> Options	Е	Т	N					
When enabled (PIN 1 is high*)								
Output	Freq. output	Freq.output	Freq. output					
Oscillator	Oscillates	Oscillates	Oscillates					
Current	Normal	Normal	Normal					
When disabled	(PIN 1 is low)							
Output	High Z state	High Z state	Freq. output					
Oscillator	Stops	Oscillates	Oscillates					
Current	Very low	Lower than normal	Normal					
When re-enabled (PIN 1 changes from low to high)								
Output recovery	Delayed	Immediate	N/A					

<sup>\*</sup> When PIN 1 is allowed to float, it is held high by an internal pull-up resistor.

## How to Order | Specify

CXOXLPN	4	D	S	E	SM3	- 32.0M	A	1	BA
Model Number	Supply Voltage Code	Shock Level Code	Special or Custom	Enable/Disable Option Code	Termination Code	Frequency Code	Accuracy at 25°C Code	Frequency Temperature Stability Code / Total Tolerance Code	Test Option Code B0 = Standard Testing Only
STXOHG CXOXLPNR CXOLATHG CXOXLPNHG HGXO CXOMKHG CXOXHG	1 = 1.8V 2 = 2.5V 3 = 3.0V 4 = 3.3V 5 = 5.0V	A = 5,000 g B = 10,000 g C = 20,000 g D = 30,000 g F = 50,000 g G = 75,000 g H = 100,000 g	S = Special or custom Blank = Standard	E, T, or N E and T are not available in all frequencies; contact factory with specific	SM1 & SM5 are Pb-free. SM3 is 60/40 Sn/Pb.	K = kHz M = MHz	A = 100 ppm D = 10 ppm F = 25 ppm G = 30 ppm H = 50 ppm X = Total Tolerance	1 = 100 ppm; -40°C to +85°C 2 = 50 ppm; -40°C to +85°C 3 = 25 ppm; -40°C to +85°C 4 = 100 ppm; -55°C to +125°C 5 = 50 ppm; -55°C to +125°C	B1 = Screening (MIL-PRF-55310) BA = Screening + Group A BB = Screening + Groups A & B BC = Screening +
CXOQHG LHGAT		11 100,000 g		requirements.	<b>CXO</b>		ESM3-32.0	DMA1BA	Groups A, B, & C

## SURFACE MOUNT AND LEADED OSCILLATORS

## **OSCILLATOR PRODUCT LEVEL B TEST OPTIONS**

	Screening	MIL-Standard	Test Method	Condition	Sample Size
	Internal Visual (Pre-Seal)	MIL-STD-883	2017 & 2032	_	100%
	Stabilization Bake (150°C)	MIL-STD-883	1008	С	100%
	Temperature Cycling	MIL-STD-883	1010	В	100%
	Constant Acceleration	MIL-STD-883	2001	A (5000g, Y1 Axis only)	100%
	Seal Test (Fine and Gross Leak)	MIL-STD-883	1014	A1 & C	100%
	PIND (Particle Impact Noise Detection)	MIL-STD-883	2020	Α	100%
	Electrical Test	-	-	_	100%
	Burn-in, operating	MIL-PRF-55310	Table III	-	100%
	Final Electrical Test	_	-	-	100%
	Group A	MIL-Standard	Test Method	Condition	Sample Size
1	Electrical Tests	MIL-PRF-55310	-	-	per MIL-PRF-55310
2	Visual & Mechanical	MIL-PRF-55310	_	_	per MIL-PRF-55310
3	Solderability	MIL-STD-202	208	-	per MIL-PRF-55310
	Group B	MIL-Standard	Test Method	Condition	Sample Size
	30-day Frequency Aging	MIL-PRF-55310	Para. 4.8.35	-	per MIL-PRF-55310
	Group C (Destructive Tests)	MIL-Standard	Test Method	Condition	Sample Size
1	Vibration	MIL-STD-202	204	D	8 Units
•	Shock	MIL-STD-202	213	F	o oniio
	Thermal Shock	MIL-STD-202	107	В	
2	Ambient Pressure	MIL-PRF-55310	Para. 4.8.46	-	4 Units
	Storage Temperature	MIL-PRF-55310	Para. 4.8.47	-	
	Resistance to Soldering Heat	MIL-STD-202	210	В	
3	Moisture Resistance	MIL-STD-202	106	-	2 Units
	Salt Atmosphere	MIL-STD-883	1009	Α	
1	Terminal Strength (as applicable)	MIL-STD-202	211	С	0.11=:t=
•	Resistance to Solvents	MIL-STD-202	215		2 Units

- The paragraph numbers listed in this table refer to MIL-PRF-55310
- Please contact factory for additional tests such as Radiographic Inspection and MIL-PRF-55310 Product Level S tests

## IN-HOUSE TEST CAPABILITIES FOR OSCILLATORS

Electrical Testing	Frequency, current, duty cycle, rise/fall time, etc.	PIND (Particle Impact Noise Detection)	MIL-STD-883, Method 2020, Conditions A-B
Temperature Testing	Frequency, current, etc. over temperature	Moisture Resistance	MIL-STD-202, Method 106
Die Shear Strength	MIL-STD-883, Method 2019	Salt Atmosphere	MIL-STD-202, Method 101, Condition B
Wirebond Pull Test	MIL-STD-883, Method 2023	Solderability	MIL-STD-883, Method 2003
Burn-In	MIL-PRF-55310 per Table III	Temperature Cycling	MIL-STD-883, Method 1010
Seal Testing	MIL-STD-883, Method 1014	Thermal Shock	MIL-STD-202, Method 107, Conditions A-B
	MIL-STD-202, Method 112		
Mechanical Shock	MIL-STD-202, Method 213, Conditions A-F	Radiographic Inspection	MIL-STD-202, Method 209
	MIL-STD-883, Method 2002, Conditions A-G		MIL-STD-883, Method 2012
Mechanical Vibration	MIL-STD-202, Method 204, Conditions A, B, D	Aging	MIL-PRF-55310, Para 4.8.35

11





#### **CX4HGSM**

5.0x1.83 mm

#### **CX11LHGSM**

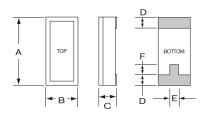
3.2x1.5 mm

	0.07	1.00 111111				0.2X1.01		
Frequency Range	14 MHz t	14 MHz to 50 MHz			16 MHz to 50 MHz			
Fundamental Frequency	14.7456 M	Hz 16 MHz	20 MHz	32 MHz	40 MHz	16 MHz	24 MHz	32 MHz
Motional Resistance R1 (Ω)	60	75	50	30	30	90	30	25
Motional Capacitance C1 (fF)	1.4	1.5	1.4	2.5	1.5	1.5	1.6	1.9
Quality Factor Q (k)	120	90	110	70	90	70	150	110
Shunt Capacitance C0 (pF)	0.8	0.9	0.9	1.1	1.0	0.7	0.7	0.9
Calibration Tolerance <sup>1</sup>	±100 ppr	n, or tighter	as requi	red		±100 ppm, or tighter as required		
Load Capacitance	10 pF (ur	nless specif	ied other	wise)		10 pF (unless specified otherwise)		
Drive Level	200 µW l	MAX				200 μW MAX		
Frequency - Temp. Stability <sup>2</sup>	±30 ppm	to ±100 ppi	m			±30 ppm to ±100 ppm		
Standard Operating Temp. Ranges	-40°C to	+85°C / -55	°C to +12	25°C		-40°C to +85°C / -55°C to +125°C		
Aging, first year	Aging is t	EPENDENT OF	N FREQUEN	ICY AND O	THER DESIGI	N CONSIDERATION	NS. PLEASE	CONTACT FACTORY.
Shock, survival <sup>3</sup>	Up to 100	0,000 g, 0.5	ms, 1/2	sine		Up to 100,000 g, 0.5 ms, 1/2 sine		
Vibration, survival <sup>4</sup>	20 g, 10-2,000 Hz swept sine					20 g, 10-	2,000 Hz sv	vept sine
Storage Temp. Range	-55°C to +125°C					-55°C to +125°C		
Max Process Temperature	+260°C f	or 20 sec.				+260°C f	or 20 sec.	

<sup>1.</sup> Other tolerances available, contact factory.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available.

#### **CX4HGSM**

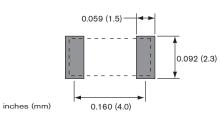


DIMENS	IONS TYP		MAX.		
DIM	inches	mm	inches	mm	
Α	0.197	5.00	0.210	5.33	
В	0.072	1.83	0.085	2.16	
С	-	-	see belo	OW	
D	0.036	0.91	0.046	1.16	
E	0.020	0.51	-	-	
F	0.025	0.64	_	_	

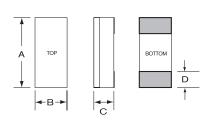
#### THICKNESS DIMENSION C (Maximum)

THICKNESS	THIORNESS DIMENSION O (MAXIMAIII)						
Temination	Glass Lid		Ceramic Lid				
	inches	mm	inches	mm			
SM1	0.045	1.14	0.050	1.27			
SM2/SM4	0.046	1.17	0.051	1.30			
SM3/SM5	0.048	1.22	0.053	1.35			

#### SUGGESTED LAND PATTERN



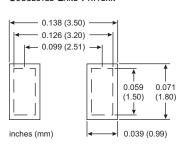
#### **CX11LHGSM**



DIMENSIONS TYP.			MAX.	
DIM	inches	mm	inches mm	
Α	0.127	3.20	0.135 3.48	
В	0.060	1.50	0.068 1.73	
С	-	_	see below	
D	0.028	0.71	0.037 0.94	

### THICKNESS DIMENSION C (Maximum)

		,	,	
Termination	Glass	Lid	Cerami	c Lid
	inches	mm	inches	mm
SM1	0.034	0.87	0.023	0.59
SM2/SM4	0.035	0.89	0.024	0.60
SM3/SM5	0.037	0.94	0.025	0.63



<sup>2.</sup> Does not include calibration tolerance. The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.

3. For over 100,000 g. Contact factory.

4. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.





## CX20HGSM

## CX16HGSM

	2.5x1.2 mm		2.0x1.2 r	2.0x1.2 mm		
Frequency Range	16 MHz to 50 MHz		24 MHz to	24 MHz to 100 MHz		
Fundamental Frequency	16 MHz	24 MHz	24 MHz	32 MHz	48 MHz	
Motional Resistance R1 (Ω)	150	50	45	45	30	
Motional Capacitance C1 (fF)	1.2	1.6	1.6	1.8	2.3	
Quality Factor Q (k)	60	80	90	60	50	
Shunt Capacitance C0 (pF)	0.7	0.8	0.7	0.8	0.8	
Calibration Tolerance <sup>1</sup>	±100, or	tighter as required	±100 ppn	±100 ppm, or tighter as required		
Load Capacitance	9 pF (un	less specified otherwise)	10 pF (u	10 pF (unless specified otherwise)		
Drive Level	200 μW	MAX	200 μW N	200 μW MAX		
Frequency - Temp. Stability <sup>2</sup>	±30 ppm	to ±100 ppm	±30 ppm	±30 ppm to ±100 ppm		
Standard Operating Temp. Ranges	-40°C to	-40°C to +85°C / -55°C to +125°C		-40°C to +85°C / -55°C to +125°C		
Aging, first year	Aging is i	AGING IS DEPENDENT ON FREQUENCY AND OTHER DESI		RATIONS. PL	LEASE CONTACT FACTORY.	
Shock, survival	Up to 100,000 g, 0.5 ms, 1/2 sine		Up to 50,	000 g, 0.5 ı	ms, 1/2 sine	
Vibration, survival <sup>3</sup>	20 g, 10-	-2,000 Hz swept sine	20 g, 10-2	2,000 Hz s\	wept sine	
Storage Temp. Range	-55°C to	+125°C	-55°C to -	+125°C		

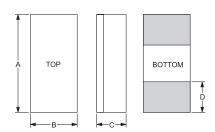
Other tolerances available, contact factory.
 Does not include calibration tolerance.

MAX Process Temperature

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available.

+260°C for 20 sec.

#### CX20HGSM



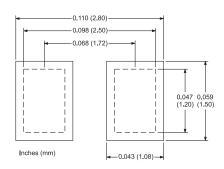
Diment	TY	P.	MAX.	
DIM	inches	mm	inches mm	
Α	0.098	2.50	0.106 2.68	
В	0.047	1.20	0.055 1.38	
С	_	_	see below	

#### D 0.030 0.75 0.035 0.88

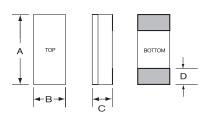
THICKNESS DIMENSION C (Maximum)					
Termination Ceramic Lid					
	inches	mm			
SM1	0.021	0.53			
SM2/SM4	0.022	0.55			

#### SUGGESTED LAND PATTERN

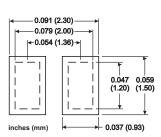
+260°C for 20 sec.



## CX16HGSM



DIMENSIONS TYP.			MAX.	
DIM	inches	mm	inches	mm
Α	0.079	2.00	0.083	2.11
В	0.047	1.20	0.056	1.42
С	0.017	0.43	0.020	0.51
D	0.026	0.66	0.029	0.74



The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.

<sup>3.</sup> Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.



#### CX18HGSM

1.6x1.0 mm

Frequency Range	30 MHz to 100 MHz			
Fundamental Frequency	32 MHz 49 MHz			
Motional Resistance R1 (Ω)	60 45			
Motional Capacitance C1 (fF)	1.0 1.2			
Quality Factor Q (k)	80 60			
Shunt Capacitance C0 (pF)	0.6 0.5			
Calibration Tolerance <sup>1</sup>	±100 ppm, or tighter as required			
Load Capacitance	9 pF (unless specified otherwise)			
Drive Level	100 μW MAX			
Frequency - Temp. Stability <sup>2</sup>	±30 ppm to ±100 ppm			
Standard Operating Temp. Ranges	-40°C to +85°C / -55°C to +125°C			
Aging, first year <sup>3</sup>	See note 3 below			
Shock, survival	Up to 75,000 g, 0.5 ms, 1/2 sine			
Vibration, survival <sup>4</sup>	20 g, 10-2,000 Hz swept sine			
Storage Temp. Range	-55°C to +125°C			
MAX Process Temperature	+260°C for 20 sec.			

- 1. Other tolerances available, contact factory.
- 2. Does not include calibration tolerance.
- The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.
- 3. Aging is dependent on frequency and other design considerations. Please contact factory.
- 4. Per MIL-STD-202, Method 204, Condition D. Random vibration testing also available.

Notes: Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice. All combinations may not be available.



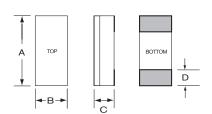
## Statek's Crystal Expertise

Statek's innovative design and manufacturing processes can support the most demanding applications. Photolithographic micromachining and ceramic packaging

expertise allows us to offer ultra-miniature highly reliable products with frequencies ranging from 1 Hz to 250 MHz, the broadest industry offering for crystal resonators and oscillators.

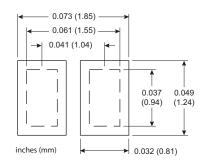


#### CX18HGSM



DIMENSIONS TYP.			MAX.		
DIM	inches	mm	inches	mm	
Α	0.063	1.60	0.066	1.68	
В	0.039	1.00	0.042	1.07	
С	0.016	0.41	0.018	0.46	
D	0.022	0.56	0.025	0.64	

#### SUGGESTED LAND PATTERN



#### How to Order | Specify CX4 HG3 S С SM3 **XMC** - 32.0M 100 / 100 / - / M Shock Level Special Lid Code Termination Code Operating Model Accuracy Screening Frequency Code or Custom Code at 25°C / Temperature Number and Code Range Code Code Frequency Stability CX4 S = Special C = Ceramic SM1, SM4, & SM5 XMA, XMB, K = kHz Blank = Standard $C = -10^{\circ}C \text{ to } +70^{\circ}C$ **Over Temp** CX11L shock level or custom Blank = Glass are Pb-free. or XMC M = MHz $I = -40^{\circ}C \text{ to } +85^{\circ}C$ Range CX16 SM2 & SM3 are M = -55°C to +125°C HG1 = 10,000 gBlank = See chart on CX18 HG2 = 20,000 gStandard 60/40 Sn/Pb. next page. As required S = Customer Specified CX20 or Combined HG3 = 30,000 gHG4 = 50,000 g Note: Other package HG5 = 75,000 g styles are available. please inquire HG6 = 100,000 g / — / 200 M CX4HG3CSM3XMC-32.0M100/100/-/M Note: Not all shock levels are available for all

packages listed.
Shock levels beyond 100,000 g are available, please consult the factory.

Statek Test Option

## **XMA**

## **CRYSTAL SCREENING OPTIONS**

Standard Testing includes: Internal Visual Inspection, Frequency & Resistance over Operating Temperature Range, Seal Test, Electrical Testing, and Final Visual Inspection.

Statek Test Option				Seal lest, Electrical lesting, and Final Visual Inspection.
Screening	Standard	Method	Condition	Comments
Internal Visual	Statek Internal Standard			Pre-seal
Unwanted Modes	MIL-PRF-3098			Spurious-mode ratio of 2:1 or greater
Frequency and Resistance over	MIL-PRF-3098			Measure every 2.5°C or tighter over the operating temperature
Operating Temperature Range				range; frequency and resistance must meet specification.
Seal Test (Fine Leak)	MIL-STD-202	112	С	
Seal Test (Gross Leak)	MIL-STD-202	112	D or E	
DLD Testing	Modified IEC 60444-6			Sweep from 10 nW to nominal drive level and back again in 1 dB steps, requiring that resistance be no greater than the maximum allowed resistance or 1.5 times the minimum resistance.
Final Electrical Test	IEC 60444	π-Network		Measure Fs, R1, C1, C0, Q, and FL
External Visual	Statek Internal Standard			Post-seal

Statek Test Option				
Screening	Standard	Method	Condition	Comments
Internal Visual	Statek Internal Standard			Pre-seal
PIND Testing	MIL-STD-883	2020	Α	Performed in both the thickness and width directions.
Unwanted Modes	MIL-PRF-3098			Spurious-mode ratio of 2:1 or greater
Frequency and Resistance over	MIL-PRF-3098			Measure every 2.5°C or tighter over the operating temperature
Operating Temperature Range				range; frequency and resistance must meet specification.
Thermal Shock	MIL-STD-202	107	В	Frequency and resistance must meet specification before and after thermal shock.
Seal Test (Fine Leak)	MIL-STD-202	112	С	
Seal Test (Gross Leak)	MIL-STD-202	112	D or E	
Accelerated Aging	MIL-PRF-3098			Aging at 105°C ± 3°C for a minimum of 168 hours. For all parts, their frequency and resistance must meet specification before and after aging. For 30 randomly selected parts, the change in series frequency must be not greater than than 5 ppm.
DLD Testing	Modified IEC 60444-6			Sweep from 10 nW to nominal drive level and back again in 1 dB steps, requiring that resistance be no greater than the maximum allowed resistance or 1.5 times the minimum resistance.
Final Electrical Test	IEC 60444	π-Network		Measure Fs, R1, C1, C0, Q, and FL
Radiographic Inspection	MIL-STD-202	209		Viewed from both the thickness and width directions.  Inspected to remove parts that are abnormal or defective.
External Visual	Statek Internal Standard			Post-seal

## IN-HOUSE TEST CAPABILITIES FOR CRYSTALS

Electrical Testing	Crystal parameters, DLD testing, spur testing, etc.	PIND (Particle Impact Noise Detection)	MIL-STD-883, Method 2020, Conditions A-B
Temperature Testing	Frequency and resistance over temperature	Moisture Resistance	MIL-STD-202, Method 106
Thermal Shock	MIL-STD-202, Method 107, Conditions A-B	Salt Atmosphere	MIL-STD-202, Method 101, Condition B
Seal Testing	MIL-STD-202, Method 112	Solderability	MIL-STD-202, Method 208
Mechanical Shock	MIL-STD-202, Method 213, Conditions A-F	Radiographic Inspection	MIL-STD-202, Method 209
	MIL-STD-883, Method 2002, Conditions A-G		MIL-STD-883, Method 2012
Mechanical Vibration	MIL-STD-202, Method 204, Conditions A, B, D	Aging	MIL-PRF-3098





Statek Corporation maintains synergetic relationships with its sister companies Greenray Industries (high precision oscillators) and Advanced Technical Ceramics Company (HTCC, ceramic feedthroughs, multilayer ALN, chemical milling, injection molding) both leaders in their respective industries. Our alliance helps us to serve our customers with leading-edge innovation and world-class manufacturing, all from a single source.





# Ultra-Miniature, High-Reliability Quartz Crystals, Oscillators and Sensors

AS9100



ISO 9001





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